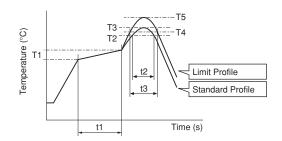
Reflow Soldering Profile

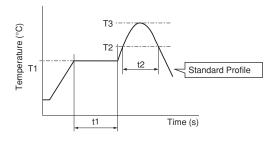
1. Soldering profile for lead free solder (96.5Sn/3.0Ag/0.5Cu)



Series	Standard Profile					Limit Profile						
	Pre-heating		Heating		Peak Temperature	Cycle	Pre-heating		Heating		Peak Temperature	Cycle
	Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)	(T3)	of Reflow	Temp. (T1)	Time (t1)	Temp. (T4)	Time (t3)	(T5)	of Reflow
	°C	sec.	°C	sec.	°C	Time	°C	sec.	°C	sec.	°C	Time
PVG3	150 to 180	60 to 120	220	30 to 60	245±3	1	150 to 180	60 to 120	230	30 to 50	260 +5/-0	2

2. Soldering profile for Eutectic solder (63Sn/37Pb)

(Limit profile: refer to 1)



	Standard Profile								
Series	Pre-h	eating	Hea	ting	Peak Temperature	Cycle			
Series	Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)	(T3)	of Reflow			
	°C	sec.	°C	sec.	°C	Time			
PVG3	150	60 to 120	183	30	230	1			

Soldering Iron

Series	Standard Condition								
	Temperature of Soldering Iron Tip	Soldering Time	Soldering Iron Power Output	Cycle of Soldering Iron					
	°C	sec.	W	Time					
PVG3	350±10	3 max.	30 max.	1					